

SOT1082-1

plastic very thin small outline package; no leads; 6 terminals;
UTLP based

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	VSON6U
Package type industry code	VSON6U
Package style descriptive code	BCC (bottom chip carrier)
Package style suffix code	U (UTLP based)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	17-6-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.4	-	3.5	3.6	mm
E	package width	2.2	-	2.3	2.4	mm
A	seated height	0.85	-	0.9	0.95	mm
e	nominal pitch	-	-	1	-	mm
n ₂	actual quantity of termination	-	-	6	-	



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2. Package outline

VSON6U: plastic very thin small outline package; no leads;
6 terminals; UTLP based; body 2.3 x 3.5 x 0.90 mm

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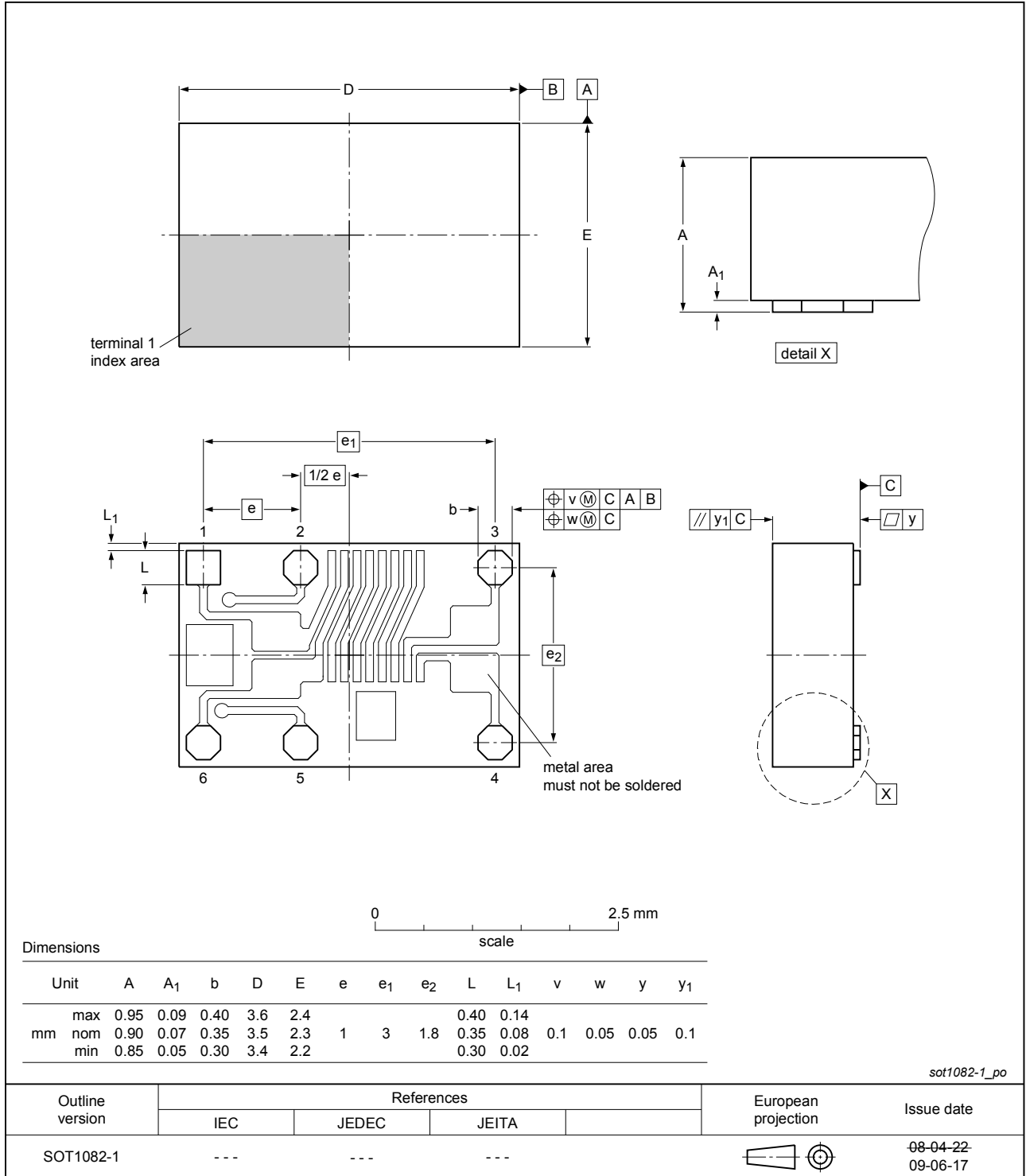


Fig. 1. Package outline VSON6U (SOT1082-1)

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3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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